



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention	METHOD OF FORMING A THERMALLY CONDUCTIVE ARTICLE USING METAL INJECTION						
Application Number:	10/605041 						
Confirmation Number:	2040						
First Named Applicant:	Kevin McCULLOUGH						
Attorney Docket Number:	C001CPP00404US2						
Art Unit:	1775						
Search string:	( T904012 or 3398322 or 3673121 or 3708387 or 40998945 or 4307147 or 4367745 or 4496475 or 4568592 or 4664971 or 4689250 or 4816184 or 5011870 or 5011872 or 5021494 or 5098610 or 5106540 or 5180513 or 5213715 or 5225110 or 5286416 or 5302456 or 5334330 or 5373046 or 5397608 or 5445308 or 5490319 or 5522962 or 5536568 or 5580493 or 5669381 or 5681883 or 5770305 or 5834337 or 5851644 or 5863467 or 5945217 or 6048919 or 4470063 or 5037590 or 5373046 or 5400505 or 5454425 or 5552214 or 5660923 or 5981085 or 6139783 or 6303096 or 20020022686 or 20020025998 ).pn.						
<b>US Patent Documents</b>							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
1	T904012	1972-11-07	Staniland		252	503	
2	3398322	1968-08-20	Lizasoain et al.		174	110	
3	3673121	1972-06-27	Meyer		252	511	
4	3708387	1973-01-02	Turner et al.		161	168	
5	40998945	1978-07-04	Oehmke		428	327	
6	4307147	1981-12-22	Ohishi et al.		428	268	
7	4367745	1983-01-11	Welage		128	303.13	
8	4496475	1985-01-29	Abrams		252	514	
9	4568592	1986-02-04	Kawaguchi et al.		428	107	
10							

10	4664971	1987-05-12	Soens
11	4689250	1987-08-25	Quella et al.
12	4816184	1987-03-28	Fukuda et al.
13	5011870	1991-04-13	Peterson
14	5011872	1991-04-30	Lathan et al.
15	5021494	1991-06-04	Toya
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21	5286416	1994-02-15	Teichmann et al.
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23	5334330	1994-08-02	Rowlette
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35	5851644	1998-12-22	McArdle et al.
36	5863467	1999-01-26	Mariner et al.
37	5945217	1999-08-31	Hanrahan
38	6048919	2000-04-11	McCullough
39	4470063	1984-09-04	Arakawa et al.
40	5037590	1991-08-06	Fukushima
41	5373046	1994-12-13	Okamura et al.
42	5400505	1995-03-28	Wei et al.
43	5454425	1995-10-03	Kao
44	5552214	1996-09-03	Kobomura et al.
45	5660923	1997-08-26	Bieler et al.

428	288
427	216
252	511
253	220
523	440
524	404
252	511
252	511
252	62.55
252	518
252	515
252	512
428	407
252	512
524	413
428	34.5
228	121
29	596
156	272.4
428	327
252	511
428	402
524	404
428	328
438	122
428	213
252	511
428	389
524	404
357	67
264	29.2
524	413
29	889
164	520
428	294
442	377

46	5981085	1999-11-09	Ninomiya et al.	428	614
47	6139783	2000-10-31	McCullough	264	40.1
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### US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
Q	1	20020022686	2002-02-21	Itoh et al.		524	504
W	2	20020025998	2002-02-28	McCullough et al.	A1	524	66

Signature

Examiner Name	Date
<i>Opuria</i>	6/28/04